



## Product/Process Change Notification Form

<b>PCN Number:</b>	PCN-2014-0487
<b>Date of Notification:</b>	7/16/2014
<b>Apex P/N(s):</b>	SA09, SA12, SA12-13
<b>Date PCN Effective:</b>	10/1/2014
<b>Reason for Change:</b>	<input type="checkbox"/> Design /New Rev. <input type="checkbox"/> Assembly Site <input checked="" type="checkbox"/> Assembly Process <input type="checkbox"/> Other (specify) Internal semiconductor chip thickness variation
<b>Description of Change:</b>	The temperature sense devices are now mounted directly to the top surface of the MOSFET output devices.
<b>Apex P/N Change:</b>	<input type="checkbox"/> Yes, New Part Number: <input checked="" type="checkbox"/> No
<b>Lot Effective Date:</b>	10/1/14
<b>Quality &amp; Reliability impact:</b>	Qualification Data: <input type="checkbox"/> Required <input checked="" type="checkbox"/> Not Required
<b>Datasheet Change Required?</b>	<input type="checkbox"/> Yes <input checked="" type="checkbox"/> No If Yes, briefly explain: